



# M T B F (E I A J R C R - 9 1 0 2 B)

Model	GT2.5W-12
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No.	Parts		Q'ty of Device	Failure rate [10 <sup>-6</sup> /H]	Reference
1	IC	Linear	4	0.0960	
2	Transistors	NPN/PNP	0	0.0000	
3	Transistors	Power NPN/PNP	2	0.0840	
4	FET	MOS FET	2	0.1980	
5	Diodes	FR	4	0.0880	
6	Diodes	Zener	2	0.0480	
7	Diodes	bridge	4	0.2640	
8	Resistors	Metal Film	32	0.5120	
9	Resistors	Power Film	6	0.2460	
10	Resistors	variable	2	0.0320	
11	Capacitors	Aluminum Electrolytic	10	0.1900	
12	Capacitors	Film	8	0.0672	
13	Transformer	Power	1	0.3600	
14	Fuses		3	0.0600	
15	Connectors	Printed Crcuit Board	9	0.4680	
16	Connection	Hand Solder	27	0.0702	
17	Connection	Flow Solder	296	0.1539	
18	Connection	Crimp	45	0.0279	
19	Connection	Screw	8	0.0080	
20	Printed Crcuit Board	Through Hole	4	0.1800	
Total Failure Rate [10 <sup>-6</sup> /H]				3.1532	

M T B F	[H]	317,000
Ambient Temperature	[°C]	-
Load Factor	[%]	-